

WHAT IS CLAIMED IS:

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2 **Sub B1** 1. A semiconductor device comprising:  
3 a. a leadframe including a plurality of leads extending therefrom, a first  
4 source attach area on a first surface of the leadframe and a first gate attach area, and a second  
5 source attach area on a second surface of the leadframe and a second gate attach area;  
6 b. at least two dies, a first of which is coupled to the first source and gate  
7 attach areas and a second of which is coupled to the second source and gate attach areas;  
8 c. a drain connection assembly coupled to a drain region of the first die;  
9 and,  
10 a body, the body being coupled to the semiconductor device such that a drain  
region of the second die is exposed.

1 2. A semiconductor device in accordance with claim 1 wherein at least  
2 one of the dies is a bumped die.

1 3. A semiconductor device in accordance with claim 2 wherein both dies  
2 are bumped dies.

1 4. A semiconductor device in accordance with claim 1 wherein the drain  
2 connection assembly comprises a drain clip and a lead rail adjacent an edge of the drain clip.

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1 5. A method of making a semiconductor device, the method  
2 comprising:  
3 providing a leadframe including a plurality of leads extending therefrom, a  
4 first source attach area on a first surface of the leadframe and a first gate attach area, and a  
5 second source attach area on a second surface of the leadframe and a second gate attach area;  
6 bonding a first die to the first source and gate attach areas with solder;  
7 reflowing the solder;  
8 bonding a second die to the second source and gate attach areas with second  
9 solder;  
10 bonding a drain connection assembly to a drain region of the second die with  
11 third solder;  
12 reflowing at least the third solder; and  
13 coupling a body to the semiconductor device such that a drain region of the  
14 second die is exposed.

- 1 6. A method in accordance with claim 5 further comprising reflowing the  
2 second solder prior to bonding the drain connection assembly to the drain region of the  
3 second die.
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